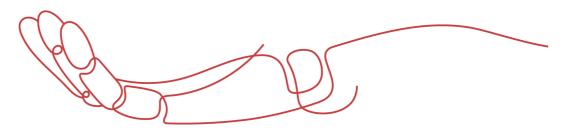


# **PRODUCT DATA SHEET**



To learn more about JGSEMI, please visit our website at



Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO\_questions@jgsemi.com.

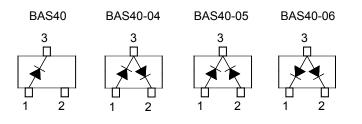


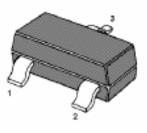
## BAS40-XX

SURFACE MOUNT SCHOTTKY BARRIER DIODE

#### Features

- Low forward voltage
- Fast switching





SOT-23

### Absolute Maximum Ratings (T<sub>a</sub> = 25 °C)

Parameter	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	40	V
DC Blocking Voltage	V <sub>R</sub>	40	V
Forward Continuous Current	I <sub>F</sub>	200	mA
Peak Forward Surge Current (at tp < 1 s)	I <sub>FSM</sub>	600	mA
Junction Temperature	TJ	150	°C
Storage Temperature Range	Ts	- 55 to + 125	°C

### Characteristics at T<sub>a</sub> = 25 °C

Parameter	Symbol	Min.	Max.	Unit
Forward Voltage at I <sub>F</sub> = 1 mA at I <sub>F</sub> = 40 mA	V <sub>F</sub> V <sub>F</sub>	-	380 1000	mV mV
Reverse Current at V <sub>R</sub> = 30 V	I <sub>R</sub>	-	200	nA
Reverse Breakdown Voltage at I <sub>R</sub> = 10 μA	V <sub>(BR)R</sub>	40	-	V
Reverse Recovery Time from $I_F = 10$ mA through $I_R = 10$ mA to $I_R = 1$ mA	t <sub>rr</sub>	-	5	ns
Total Capacitance at V <sub>R</sub> = 0 V, f = 1 MHz	CT	-	5	pF

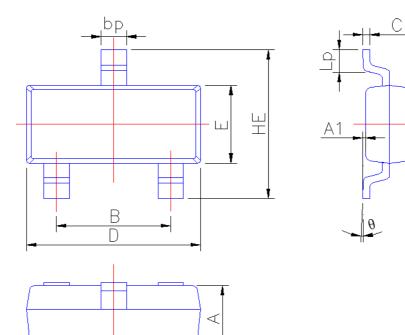
Ver.1.0





#### PACKAGE OUTLINE

#### Plastic surface mounted package; 3 leads



Symbol	Dimension in Millimeters		
	Min	Мах	
А	0.90	1.10	
A1	0.013	0.100	
В	1.80	2.00	
bp	0.35	0.50	
С	0.09	0.150	
D	2.80	3.00	
Е	1.20	1.40	
HE	2.20	2.80	
Lp	0.20	0.50	
θ	0°	5°	

#### SOT-23





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